

Amendments to the Claims:

This listing of claims will replace all prior versions, and listing, of claims in the application:

Listing of Claims:

Claim 1 (original): A method for depositing a thickfilm dielectric on a substrate, comprising:

- a) depositing a first layer of thickfilm dielectric on the substrate;
- b) air drying the first layer to allow solvents to escape, thereby increasing the porosity of the first layer;
- c) oven drying the first layer;
- d) depositing additional layers of thickfilm dielectric on top of the first layer, oven drying after the deposition of each additional layer; and
- e) firing the deposited layers.

Claim 2 (original): The method of claim 1, wherein the first layer is air dried for at least 45 minutes.

Claim 3 (original): The method of claim 1, wherein said oven drying of the first layer comprises oven drying at a peak temperature of about 150°C for about fifteen minutes.

Claim 4 (original): The method of claim 3, wherein said oven drying of the additional layers comprises oven drying at a peak temperature of about 150°C for about fifteen minutes.

Claim 5 (original): The method of claim 1, wherein said firing comprises firing at a peak temperature of about 850°C.

Claim 6 (original): The method of claim 1, further comprising measuring a dry print thickness of the deposited layers to determine if a desired final dielectric thickness will be achieved after the deposited layers are fired.

Claim 7 (original): The method of claim 6, wherein the dry print thickness of the deposited layers is measured using one of a drop-gauge micrometer or stylus profilometer.

Claim 8 (original): The method of claim 6, wherein the dry print thickness of the deposited layers is measured using a drop-gauge micrometer.

Claim 9 (original): The method of claim 1, wherein the layers of thickfilm dielectric comprise a KQ dielectric.

Claim 10 (original): The method of claim 9, wherein the KQ dielectric is KQ CL-90-7858 dielectric.

Claim 11 (original): The method of claim 10, further comprising, after firing, grinding the deposited layers to a desired final dielectric thickness, and then refiring the deposited layers to smooth the ground surface and edges.

Claim 12 (original): The method of claim 1, wherein the layers of thickfilm dielectric comprise a glass dielectric.

Claim 13 (canceled)

Claim 14 (original): The method of claim 1, wherein the layers of thickfilm dielectric are deposited by printing the layers through a stainless steel screen having 200 mesh, 1.6 mil wire, .8 mil emulsion.

Claim 15 (original): The method of claim 1, further comprising depositing additional layers of thickfilm dielectric until a dry print thickness in excess of a desired dry print thickness is achieved, and then planarizing the deposited layers to a desired dry print thickness prior to firing the deposited layers.

Claim 16 (original): The method of claim 1, further comprising, after firing, grinding the deposited layers to a desired final dielectric thickness, and then polishing the ground surface.

Claim 17 (original): The method of claim 1, wherein the first layer is air dried for at least 45 minutes, wherein said oven drying of the first layer comprises oven drying at a peak temperature of about 150°C for about fifteen minutes, wherein said oven drying of each additional layer comprises drying at a peak temperature of about 150°C for about five minutes, and wherein said firing comprises firing at a peak temperature of about 850°C.

Claim 18 (original): The method of claim 17, wherein the thickfilm dielectric comprises KQ CL-90-7858 dielectric.

Claim 19 (canceled)

Claim 20 (original): The method of claim 18, further comprising, after firing, grinding the deposited layers to a desired final dielectric thickness, and then refiring the deposited layers to smooth the ground surface and edges.